

Description

The DMP3036SSD uses advanced trench technology and design to provide excellent R_{DS(ON)} with low gate charge. It can be used in a wide variety of applications.

General Features

 $V_{DS} = -30V, I_{D} = -11A$

 $R_{DS(ON)}$ < 18m @ V $_{GS}$ =-10V

 $R_{DS(ON)}$ < 27m @ V GS=-4.5V

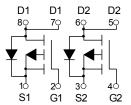
Application

PWM application

Load switch



SOP-8



Dual P-Channel MOSFET

Package Marking and Ordering Information

Product ID	Pack	Brand	Qty(PCS)
DMP3036SSD	SOP-8	HXY MOSFET	3000

Absolute Maximum Ratings (T_A=25[°]C unless otherwise noted)

Symbol	Parameter	Limit	Unit
V _{DS}	Drain-Source Voltage	-30	V
V _G s	Gate-Source Voltage	±20	V
l _D	Drain Current-Continuous	-11	Α
Ірм	Drain Current-Pulsed (Note 1)	-40	Α
Po	Maximum Power Dissipation	3.7	W
T _J ,T _{STG}	Operating Junction and Storage Temperature Range	-55 To 150	$^{\circ}$
Reja	Thermal Resistance,Junction-to-Ambient (Note 2)	33.8	°C/W



$\textbf{Electrical Characteristics} \ \, (T_J = 25\, ^{\circ} \! \text{C unless otherwise specified})$

Symbol	Parameter	Test Condition	Min.	Тур.	Max.	Units	
V _{(BR)DSS}	Drain-Source Breakdown Voltage	V _{GS} =0V, I _D = -250μA	-30	-	-	V	
I _{DSS}	Zero Gate Voltage Drain Current	V _{DS} = -30V, V _{GS} =0V,	-	-	-1	μΑ	
I _{GSS}	Gate to Body Leakage Current	V _{DS} =0V, V _{GS} = ±20V	-	-	±100	nA	
V _{GS(th)}	Gate Threshold Voltage	$V_{DS}=V_{GS}$, $I_D=-250\mu A$	-1.0	-1.6	-2.5	V	
В	Static Drain-Source on-Resistance	V _{GS} = -10V, I _D = -10A	-	14	18	mΩ	
R _{DS(on)}	Note3	V _{GS} = -4.5V, I _D = -5A	-	20	27		
C _{iss}	Input Capacitance	\/ - 45\/ \/ -0\/	-	1330	-	pF	
Coss	Output Capacitance	V_{DS} = -15V, V_{GS} =0V, f=1.0MHz	-	183	-	pF	
C _{rss}	Reverse Transfer Capacitance	1-1.0IVII 12	-	156	-	pF	
Qg	Total Gate Charge	\/ 45\/ L 5A	-	22	-	nC	
Q _{gs}	Gate-Source Charge	V_{DS} = -15V, I_{D} = -5A, V_{GS} = -10V	-	1.0	-	nC	
Q_{gd}	Gate-Drain("Miller") Charge	VGS10V	-	1.8	-	nC	
t _{d(on)}	Turn-on Delay Time		-	9	-	ns	
t _r	Turn-on Rise Time	V_{DD} = -15V, I_{D} = -10A, V_{GS} =-10V, R_{GEN} =2.5 Ω	-	13	-	ns	
t _{d(off)}	Turn-off Delay Time		-	48	-	ns	
t _f	Turn-off Fall Time		-	20	-	ns	
Is	Maximum Continuous Drain to Source Diode Forward Current		-	-	-11	А	
I _{SM}	Maximum Pulsed Drain to Source Diode Forward Current		-	-	-40	Α	
\/	Drain to Source Diode Forward	V _{GS} =0V, I _S = -15A	-	-0.8	-1.2	V	
V _{SD}	Voltage	VGS-UV, IS15A					
trr	Reverse Recovery Time	TJ=25℃,	1	64	-	ns	
Qrr	Reverse Recovery Charge	V_{DD} = -24 V , I_F =-2.8 A , dI/dt =-100 $A/\mu s$	-	25	-	nC	

Notes:1. Repetitive Rating: Pulse Width Limited by Maximum Junction Temperature

- 2. EAS condition: $T_J = 25\,^{\circ}\!\!\mathrm{C}$, $V_{GS} = 10V$, $R_G = 25\Omega$, L=0.5mH, $I_{AS} = -12.7A$
- 3. Pulse Test: Pulse Width≤300µs, Duty Cycle≤0.5%



Typical Performance Characteristics

Figure1: Output Characteristics

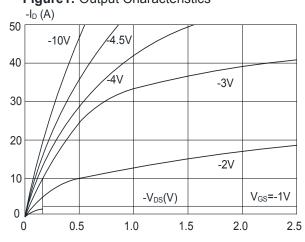


Figure 2: Typical Transfer Characteristics

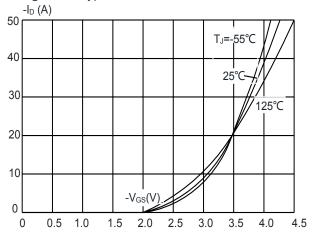


Figure 3:On-resistance vs. Drain Current

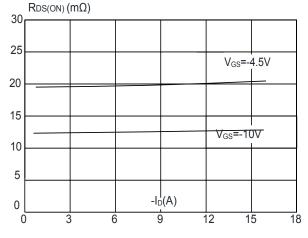


Figure 4: Body Diode Characteristics

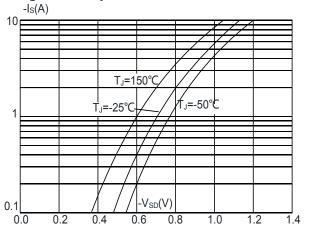


Figure 5: Gate Charge Characteristics

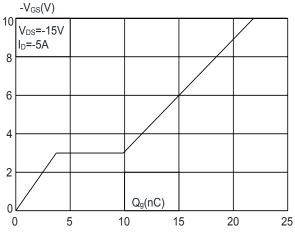


Figure 6: Capacitance Characteristics

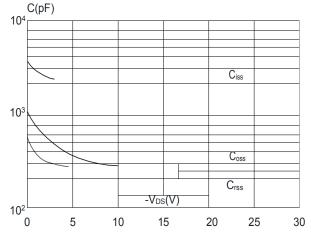




Figure 7: Normalized Breakdown Voltage vs. Junction Temperature

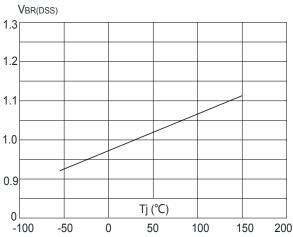


Figure 9: Maximum Safe Operating Area

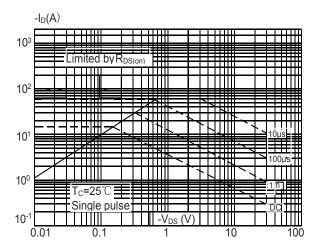


Figure.11: Maximum Effective Transient Thermal Impedance, Junction-to-Case

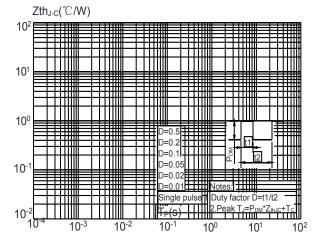


Figure 8: Normalized on Resistance vs. Junction Temperature

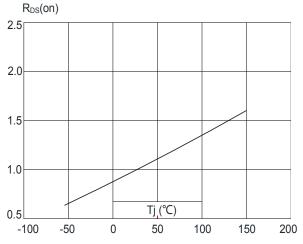
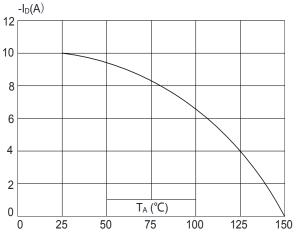


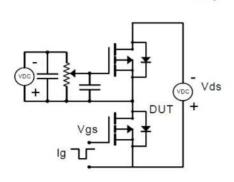
Figure 10: Maximum Continuous Drain Current vs. Ambient Temperature

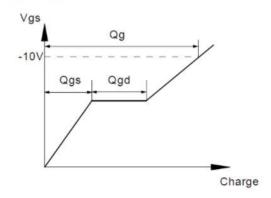




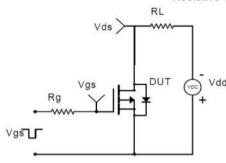
Test Circuit

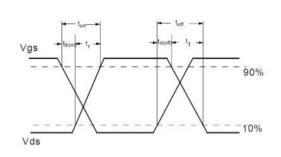
Gate Charge Test Circuit & Waveform



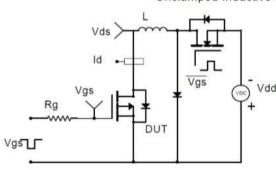


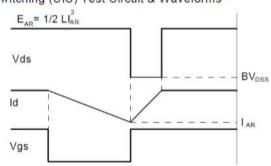
Resistive Switching Test Circuit & Waveforms



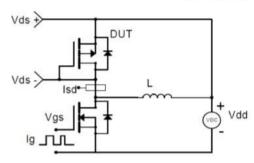


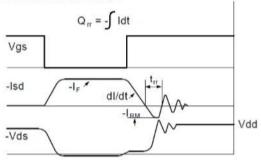
Unclamped Inductive Switching (UIS) Test Circuit & Waveforms





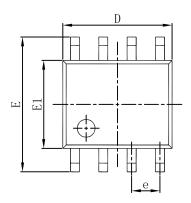
Diode Recovery Test Circuit & Waveforms

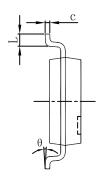


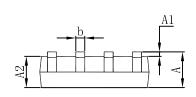




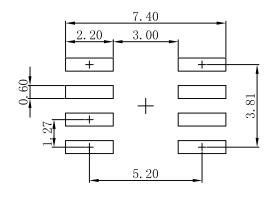
SOP-8 Package Outline Dimensions







Symbol	Dimensions In Millimeters		Dimensions In Inches		
Symbol	Min	Max	Min	Max	
A	1.350	1.750	0.053	0.069	
A1	0.100	0. 250	0.004	0.010	
A2	1. 350	1.550	0.053	0.061	
b	0.330	0.510	0.013	0.020	
С	0. 170	0. 250	0.007	0.010	
D	4.800	5.000	0. 189	0. 197	
e	1.270 (BSC)		0.050 (BSC)		
E	5.800	6. 200	0. 228	0. 244	
E1	3.800	4.000	0.150	0. 157	
L	0.400	1.270	0.016	0.050	
θ	0°	8°	0°	8°	



- Note: 1.Controlling dimension:in millimeters.
- 2.General tolerance:± 0.05mm.
 3.The pad layout is for reference purposes only.



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